table 21 in advance to set the temperature of the placing table 21 at a predetermined temperature. In step S31, the glass substrate G is loaded onto the placing table 21 by the main arm serving as a convey means and delivered to the support pins 21. Thereafter, the support pins 23 are moved downward to place the glass substrate G on the placing table 21. In step S31 or before or after step S31, the second electromagnetic valves 34 and 35 are closed and the first electromagnetic valves 32 and 33 are opened in step S32 to supply a coolant having a temperature lower than a predetermined temperature, e.g., 18°C from the first coolant supply means 30 into the coolant path 28. In step S32, as a timing at which the supply of the coolant is switched, for example, the coolant supply may be switched the moment a proper sensor (not shown) detects that the glass substrate G is loaded onto the placing table 21, otherwise, the coolant supply may be switched a predetermined time after the sensor detects that the glass substrate G is loaded onto the placing table 21. In addition, for example, the coolant supply may be switched the moment a command for loading the glass substrate G into the cooling device 14 is output to the main arm 9, otherwise, the coolant supply may be switched a predetermined time after the command for loading the glass substrate G into the cooling device 14 is output.

IN THE CLAIMS

Please cancel Claims 1-14. Please add new claims 15-17 as follows:

15. (New) A cooling method for cooling a substrate loaded on a placing table by supplying a coolant having a temperature lower than a target temperature into a coolant path arranged in said placing table, comprising the steps of:

(A3) setting in advance the temperature of the placing table at a temperature almost equal to said target temperature;